

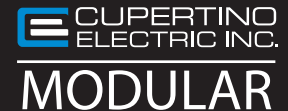
# CEI MODULAR FEATURING COOLED-BY-ZUTACORE

*to Densify Data Centers, Lower Costs and Reduce Complexity*

CEI Modular designs, integrates, deploys and commissions solutions with data center operator needs in mind. As high-performance computing cooling demands increase and air solutions reach their limit, operators are struggling with effective cooling solutions that do not involve water, which could lead to risk of IT meltdown. CEI Modular exists to solve these kinds of challenges. Leveraging extensive insight to anticipate problems and plan for the entire product life cycle, CEI Modular vets technologies, then **designs, builds, tests and delivers** high-quality, complete solutions.

By incorporating ZutaCore's direct-on-chip, two-phase, **waterless** liquid cooling solution into its modular data center designs, CEI Modular is revolutionizing the data center. With the HyperCool<sup>2™</sup> inside, CEI Modular is shrinking the data center footprint up to **40 percent**, simplifying design, streamlining installation and **densifying computing**. ZutaCore's liquid cooling solution is the latest technology in CEI Modular's portfolio of modular data center designs.

Together, CEI Modular and ZutaCore's HyperCool<sup>2™</sup> provide the most innovative technology along with a flexible, cost-effective alternative to traditional data center construction. Pre-designed to match emerging business needs, pre-tested to work every time and built in a controlled environment to ensure the highest quality, the result is a CEI Modular data center with the same performance and reliability as stick built, but with faster delivery and minimized risk for quicker revenue generation.





# MODULAR



*For more information about  
CEI Modular cooled-by-ZutaCore  
solutions, please contact us at  
[modular@cei.com](mailto:modular@cei.com).*

## **SOLUTION OVERVIEW**

- ZutaCore HyperCool<sup>2</sup>™ system offered by industry leader CEI Modular
- Partnership with trusted modular and manufacturing partner

## **YOUR MODULAR DATA CENTER SOLUTION FOR**

- Direct-on-chip cooling to alleviate cooling boundaries
- On demand liquid cooling with a safe, non-conductive refrigerant

## **BENEFITS**

- Unparalleled heat dissipation with no risk of IT meltdown
- Triple computing densities on one-third of the footprint